

## COMSOL<sup>®</sup> Simulation of Flash Lamp Annealed Multilayers for Solid State Electrolyte Fabrication C. Cherkouk<sup>1</sup>, L. Hell, M. Zschornak<sup>1</sup>, T. Leisegang<sup>1</sup>, D.C. Meyer<sup>1</sup> Institute of Experimental Physics, Technische Universität Bergakademie Freiberg, Leipziger Straße 23, 09596 Freiberg, Germany



**INTRODUCTION**: Flash lamp annealing (FLA) is a modern annealing technique in the range of milliseconds, which is predestinated for roll-to-roll fabrication of battery electrodes. However, the existing methods for a direct temperature measurement, like pyrometry for FLA, are unable to detect background radiation of the intense flash light, emissivity and the shadow effect. COMSOL Multiphysics<sup>®</sup> is used in order to model thermal cycling of FLA and the temperature distribution through Si/SiO<sub>2</sub>/Al<sub>2</sub>O<sub>3</sub> layers. Furthermore, since on a time scale of only a few milliseconds heat dissipation is dominated by heat conduction towards the substrate, two sample holder of FLA of both steel and quartz are investigated.

**RESULTS:** FLA lamps are capable to generate pulse durations between 0.5 and 20 ms. The spectral energy of the lamps is ranged between 400 – 800 nm. Both the 1.27 ms pulse and spectrum of Xe-lamps were experimental measured and implemented in



## the model.



**Figure 2**. Temperature distribution of the surface using steel and quartz holder at 0.005s flash pulse. The emissivity  $\varepsilon$  of Al<sub>2</sub>O<sub>3</sub> is set to 0.2



Figure 1. Two configurations of FLA sample holder using steel and quartz rods

**COMPUTATIONAL METHODS**: Computational Methods: FEM was utilized using the COMSOL Multiphysics<sup>®</sup> code. The Heat Transfer with Surface-To-Surface Radiation interface contains the heat transfer in solid (eq.1) and irradiative flux of the external source (eq.2) as well as a diffuse surface boundary including on the radiation process (eq.3):

$$\rho C_{p} \frac{\partial T}{\partial t} + \rho C_{p} \mathcal{U} \cdot \nabla T + \nabla (-\kappa \nabla T) = Q \quad (1)$$

$$G_{ext} = F_{ext}(x_{s}) \cdot P_{s}$$

$$x_{s} = (0,0, d_{z} = 10cm) \quad (2)$$

**Figure 3**. (left) T(t) simulation on layer stacks after FLA treatment using a steel holder and (right) maximum temperature on the top of  $Al_2O_3$  as function of the emissivity  $\varepsilon$ 

- No accurate data for emissivity of Al<sub>2</sub>O<sub>3</sub> in literature. The found values vary between 0.1 and 0.4
- The value of  $\varepsilon$  implemented influences strongly the maximum temperature on the top of Al<sub>2</sub>O<sub>3</sub> layer.
- T maxima are comparable for both FLA setup using steel and quartz holder
- T(t) decreases very slowly using quartz holder

**CONCLUSIONS**: COMSOL<sup>®</sup> was used to simulate temperature distribution on  $Si/SiO_2/Al_2O_3$  using FLA treatment. It was shown how different parameter, e.g. the surfaces emissivity or the both geometries

$$e_b(T) = n^2 \cdot \sigma \cdot T^4 \tag{3}$$

**Mesh**: For the modeling physics-controlled meshing and adaptive mesh refinement were used. The top thin layer was finer meshed by sweeping perpendicular to the sweep direction. influence the heat distribution. However, the strongest effect which causes the shifting towards lower or higher temperatures is the surface emissivity.

## Acknowledgments

We gratefully acknowledge financial support from:

- Federal Ministry of Education and Research:R2R (FKZ 03SF0542A)
- The Development Bank of Saxony: SiNergy Project (100256790)

